

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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In re application of:

Dickensheets et al.

Serial No.: Not yet assigned

Filed: Herewith

For: *MINIATURE SCANNING CONFOCAL
MICROSCOPE*

Art Unit: not assigned

Examiner: not assigned

Date: April 28, 1998

"EXPRESS MAIL" MAILING LABEL NUMBER EM445772425US

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Signed:

Evanjelin Dasalla

Transmitted herewith is a preliminary amendment in the above-entitled application.

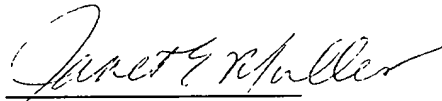
The fee has been calculated as shown below.

(1) Claims Remaining After Amendment	(2) Highest Previously Paid For	(3) Present SMALL ENTITY OR Extra RATE FEE	(4) OTHER THAN A SMALL ENTITY RATE FEE
TOTAL CLAIMS <u>10</u>	- <u>20</u>	<u>0</u> x11 = \$ <u> </u> OR	x22 = \$ <u> </u>
INDEP CLAIMS <u>1</u>	- <u>3</u>	<u>0</u> x41 = \$ <u> </u> OR	x82 = \$ <u> </u>
[x] Multiple Dependent Claim Presented And Fee Not Previously Paid		+135 = \$ <u>135</u>	OR +270 = \$ <u> </u>
		TOTAL \$ <u>135</u>	OR TOTAL \$ <u> </u>

X Our Check in the amount of \$ \$135.00 is enclosed to cover the fee for multiple dependencies.

x Please charge any additional fees, including extension fees, or credit any overpayment to
Deposit Account No. 06-1300 (Order No. A-62591-3/AJT).

Respectfully submitted,



Janet E. Muller, Reg. No. 35,294
/for/Aldo J. Test. Reg. No. 18,048

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A

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Docket No. A-62591-3/AJT

Anticipated Classification of
this Application:

Class: Subclass:

Prior Application: 08/797,931

Examiner: Not yet assigned

Art Unit: 2507

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NUMBER EM445772425US

DATE OF DEPOSIT April 30, 1998

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TYPED NAME Evangelin Dasalla

SIGNED [Signature]

Box PATENT APPLICATION FEE

Assistant Commissioner for Patents
Washington, DC 20231

Sir:

This is a request for filing a continuation application under 37 C.F.R. 1.53(b), in the names of David L. Dickensheets and Gordon S. Kino, for MINIATURE SCANNING CONFOCAL MICROSCOPE. This continuation claims priority to pending application Serial No. 08/797,931 filed on February 12, 1997, which is a continuation-in-part of application Serial No. 08/575,687 filed December 19, 1995.

1. x Enclosed is a copy of the prior application.
2. (a) Enclosed is a new Declaration.
(b) X Enclosed is a copy of the prior executed Declaration as originally filed.
3. (a) Enclosed is a Small Entity Affidavit.
(b) X A Small Entity Affidavit is of record in the prior application.

4. X The filing fee is calculated below:

Claims as filed in the prior application, less any claims canceled by amendment below:

FOR:	(Col. 1) NO. FILED	(Col. 2) NO. EXTRA	SMALL ENTITY		OR	OTHER THAN A SMALL ENTITY	
			RATE	FEE		RATE	FEE
BASIC FEE				\$395	OR		\$790
TOTAL CLAIMS	<u>1</u> -20 =	<u>0</u>	x11 =	\$	OR	x22 =	\$
INDEP CLAIMS	<u>1</u> -3 =	<u>0</u>	x41 =	\$	OR	x82 =	\$
[] MULTIPLE DEPENDENT CLAIM PRESENTED			+135 =	\$	OR	+270 =	\$
*If the difference in Col. 1 is less than zero, enter "0" in Col. 2.			TOTAL	<u>\$395</u>	OR	TOTAL	<u>\$</u>

5. X The Commissioner is hereby authorized to charge any additional fees which may be required, including extension fees, or credit any overpayment to Deposit Account No. 06-1300 (Order No. A-62591-3/AJT).

6. X Our check in the amount of \$395.00 is enclosed.

7. x Cancel in this application original claims 2-19 of the prior application before calculating the filing fee. (At least one independent claim must be retained for filing purposes.)

8. x Amend the specification by inserting before the first line the sentence:

-- This is a continuation of application Serial No. 08/797,931 filed February 12, 1997.--

9. (a) _____ Informal drawings are enclosed.
(b) x Formal drawings are enclosed.

10. A prior art statement is enclosed with cited references.

11. x The prior application is assigned of record to Board of Trustees of the Leland Stanford Junior University, The.

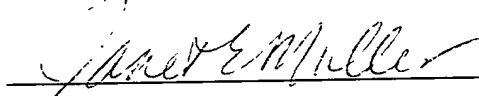
12. (a) x The power appears in the original papers in the prior application.

(d) x Address all future communications to:

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13. x A preliminary amendment is enclosed. (Claims added by this amendment have been properly numbered consecutively beginning with the number next following the highest numbered original claim in the prior application.)
14. x Also enclosed is a separate transmittal for the preliminary amendment and a check for \$135.00 to cover the fee for multiple dependencies.
15. x I hereby verify that the attached papers are a true duplicate of prior application Serial No. 08/797,931 as originally filed on February 12, 1997.

Date: April 30, 1998


Janet E. Muller, Reg. No. 35,294

/for/ Aldo J. Test, Reg. No. 18,048

Address of Signer: x Attorney or agent of record

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BOX PATENT APPLICATION

Assistant Commissioner for Patents

Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

Please amend the referenced application as follows:

IN THE SPECIFICATION:

On page 15, line 4, delete the "δ" before the "θ" and delete the word "separation" and insert in place thereof -- angle --.

On page 16, line 13, delete "δθ" and insert in place thereof -- h --.

IN THE CLAIMS

Cancel Claim 1.

Please add the following claims:

20. Apparatus for viewing a medium, comprising:
a support member movably mounted relative to said medium;
an optical fiber having one end fixedly mounted on said support member;
a focusing member mounted on said support member between said one end of the optical fiber and said medium for focusing a beam from said optical fiber onto said medium; and
at least one micromachined active beam deflection mirror means on said support member between said optical fiber and said medium, for deflecting said beam to focus the beam at selected locations on said medium independent of movement of the support member relative to said medium.

21. Apparatus according to Claim 20 wherein the optical fiber is a single-mode optical fiber.

22. An apparatus as in either Claim 20 or 21 in which the mirror means comprises a first micromachined scanning mirror to receive light from the optical fiber and scan the light along a first direction and a second micromachine scanning mirror to receive light from the first mirror and scan the light in an orthogonal direction.

23. An apparatus as in Claim 20 or 21 in which the mirror means comprises a frame which is supported by nitride hinges for rotation about a first axis, and a micromachined mirror supported from said frame by nitride hinges for rotation about an orthogonal axis and whereby said mirror scans the light at first and second orthogonal directions.

24. Apparatus according to Claim 20 or 21 wherein the beam is reflected back from said medium to said optical fiber along substantially the same optical path said beam took from said optical fiber to said medium.

25. Apparatus according to Claim 22 wherein the beam is reflected back from said medium to said optical fiber along substantially the same optical path said beam took from said optical fiber to said medium.

26. Apparatus according to Claim 23 wherein the beam is reflected back from said medium to said optical fiber along substantially the same optical path said beam took from said optical fiber to said medium.

Respectfully submitted,

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MINIATURE SCANNING CONFOCAL MICROSCOPE

Reference to Related Applications

The present application is a continuation in part of U.S. Patent Application Ser. No. 08/575,687, filed December 19, 1995.

5

Brief Description of the Invention

This invention relates generally to miniature confocal microscopes and more particularly to scanning confocal microscopes using micro-machined mirrors.

Background of the Invention

10 The standard optical microscope, used routinely in biology, medicine and semiconductor processing, is large. Typically, samples of tissue are observed *in vitro* after being mounted on a microscope slide. Such microscopes are not suitable for *in vivo* observations of the skin or internal organs of the human body; they are just too large. Consequently, there is a need for a small microscope which could be used for observations of melanomas of the skin, and the teeth and gums, and for endoscopy of cells inside
15 arteries and veins and organs of the body. Ultimately, if such a microscope could be mounted inside a hypodermic needle, it would be suitable for taking *in vivo* biopsies and for observing microscopic features of the body, such as the flow of blood and plasma in veins, arteries, and other vessels of the body, the fluid in tear ducts, and the general condition of small vessels. Although we have described biological applications of a
20 miniature microscope, the miniature microscope of the present invention can be used in endoscopes passed through small pipes, and for use *in-situ* observation during processing of semiconductors and other materials.

The present tendency is to carry out clinical procedures with small tools mounted in catheters, to make internal observations inside vessels with fiber optic devices, and to
25 carry out operations using laser and fiber-optic techniques. Much less damage is done to the body than with older surgical methods by using such procedures. Observations of what

is being done on a microscopic scale would be helpful, since the best resolution that presently can be obtained with endoscopes is of the order of 10-20 μm . Another example is the observation of cancer cells in the uterus, where it is extremely painful to carry out biopsies. An *in vivo* imaging technique for this purpose which leaves the tissue intact would be a considerable improvement over present practice.

Several fiber optic microscopes have been suggested in the past, but either they are too bulky or too slow, so that the frame time is of the order of several seconds, or the definition is very poor¹⁻⁶. Thus, these microscopes are not suitable for *in vivo* real-time imaging at the microscopic level.

We reported a vibrating fiber microscope in a recent paper⁷. A Fresnel lens made by photolithographic means was mounted on the end of a vibrating glass rod approximately 0.8 mm square. The lens was illuminated from an optical fiber glued to the other end of the rod, and formed a spot of the order of 1.8 μm in diameter at an approximate distance of 1 mm from the lens. Light reflected from the object being observed was passed back through the fiber and lens to a detector. The signal from the detector, after suitable processing, was displayed through an image converter as a video image. The rectangular-shaped rod was vibrated by electrostatic fields, applied between it and an outer tube, at its slightly different mechanical resonant frequencies in the *x* and *y* directions. Hence, the focused spot from the lens formed a raster pattern (a Lissajous figure). The vibration frequencies were of the order of 8 kHz, and a single frame of the image took about 1/20 second to form. The resolution was about 2 μm . This microscope suffered from the disadvantage that the vibrating rod needed support from a rigid and massive structure, which made the supporting structure large and unsuitable for use in the body.

Objects and Summary of the Invention

It is an object of this invention to provide a micro-machined miniature scanning optical microscope.

It is another object of the invention to provide a miniature scanning optical microscope using micro-machined, electrostatically actuated scanning mirrors.

It is still another object of the invention to provide a miniature scanning optical microscope using micro-machined, electrostatically actuated scanning mirrors and a micro-machined binary lens.

There is provided a scanning optical microscope which incorporates electrostatically actuated scanning mirrors disposed between a single-mode optical fiber light source/

5 detector and a focusing objective lens.

Brief Description of the Drawings

The foregoing and other objects of the invention will be more fully understood from the following description read in connection with the accompanying drawings, of which:

10 Figure 1 is a perspective view of a miniature confocal scanning microscope in accordance with the invention;

Figure 2 is an exploded view showing the parts of the microscope of Figure 1;

Figure 3 is a sectional view taken along the line 3-3 of Figure 1;

Figure 4 is a sectional view taken along the line 4-4 of Figure 1;

15 Figure 5 is a sectional view taken along the line 5-5 of Figure 1;

Figure 6 shows the zone plate line schematically illustrated in Figures 1 and 2;

Figure 7 shows the angles employed in the design of an off-axis zone plate lens;

Figure 8 shows the optical fiber illumination/detection configuration;

Figure 9 shows an open-loop electronic drive circuit associated with the scanning

20 mirrors and the signal processing circuit

Figure 10 shows a closed-loop electronic drive circuit associated with the scanning mirrors and the signal processing circuit;

Figure 11 shows an image of chrome lines on a glass substrate taken with a microscope in accordance with the invention;

25 Figure 12 shows another image of chrome lines on a glass substrate taken with a microscope in accordance with the invention;

Figure 13 shows an image of a silicon test structure taken with a microscope in accordance with the invention; and

Figure 14 shows an image of red blood cells taken with a microscope in accordance

30 with the invention.

Figure 15 is an exploded view of another embodiment of the scanning mirrors and substrates shown in Figures 1-4.

Figure 16 is a partial sectional view of one of the scanning mirrors shown in Figure 15.

5 Figure 17 is a top plan view of the mirror shown in Figure 16.

Figure 18 is a sectional view of a scanning microscope incorporating a detector.

Figure 19a is an enlarged view of the portion 19-19 of Figure 18.

Figure 19b is an end view of the single mode optical fiber.

10 Figure 20 is a sectional view of a scanning microscope head showing a refractive focusing lens.

Figure 21 is a sectional view of a scanning microscope employing a biaxial scanning mirror.

Figure 22 is a top plan view of the biaxial scanning mirror of Figure 21.

Figure 23 is a sectional view of the biaxial scanning mirror of Figure 22.

15 Figure 24 shows the frequency response of both the inner plate and the combined inner plate and outer frame.

Figure 25 shows the frequency response for the inner plate for a range of values of common mode dc bias voltage.

20 Figure 26 shows the angular deflections of mirror and frame as a function of dc bias voltage.

Figure 27 shows a chrome bar target image by a microfabricated confocal microscope in accordance with Figure 21.

Figure 28 shows a miniature confocal scanning microscope mounted in a hypodermic tubing.

25 Description of the Preferred Embodiment

A miniature scanning confocal microscope in accordance with the invention is illustrated in the perspective view of Figure 1, the exploded view of Figure 2 and the sectional views of Figures 3-5. The microscope includes a silicon substrate 11, a bonded silicon plate 12, a single mode optical fiber 13, a silicon spacer 14 and a fused silica lens plate 16 bonded to the silicon spacer 14. The plate 12 includes a pair of micro-machined

30

scanning mirrors 17, 18 disposed between the single mode optical fiber 13 and a miniature objective lens 19 formed in the silica lens plate 16. The silicon spacer comprises $\langle 100 \rangle$ silicon which is etched to form an opening 21 which forms a $\langle 111 \rangle$ face 22. Referring to Figure 3, the light beam 23 from the fiber 13 is first reflected from the etched $\langle 111 \rangle$ face 22 onto the first scanning mirror 17, then from a metallized mirror 24 on the lens plate 16 back to the second scanning mirror 18. The light beam is then reflected from the second scanning mirror 18 and passes through an off-axis zone plate objective lens 19 etched into the fused silica lens plate 16. The lens images the output from the fiber to a point 26 on the sample plane. As the mirrors rotate, this point is scanned through the field of view. Light reflected back from the sample is re-imaged by the lens 19, back along the same path to the fiber, and is detected and processed to create an image. Since the fiber behaves like a small pinhole, the device is a confocal microscope with the range and transverse resolution to be expected from a confocal scanning-optical microscope.

The mirror scanners are fabricated using silicon micro-machining techniques. Micro-machined torsional mirrors for use in scanners and spatial light modulators have been reported by numerous authors.⁸⁻¹⁴ The rotational axes of the two mirrors are orthogonal, so that one mirror scans the light beam in the x-dimension and the other mirror scans it in the y-dimension. As will be presently described, the mirrors 17, 18 are electrostatically rotated.

The silicon substrate 11 is masked and etched to form spaced wells 28, 29 below the mirrors 17, 18 whereby the mirrors can rotate. The substrate is masked and impurities are implanted into the substrate to form conductive regions. More particularly, two conductive regions 31, 32 are formed at the bottom of well 28 and two conductive regions 33, 34 are formed at the bottom of the well 29. These regions are connected to ion-implanted contact regions 36, 37 and 38, 39 by ion-implanted leads 41, 42 and 43, 44. A bonding thermal oxide layer 46 is formed on the surface. A silicon nitride cap is formed over the oxide in the wells 28, 29 to provide insulation during a subsequent metallization step.

The silicon plate 12 is bonded to the substrate via an oxide layer on the plate and the substrate oxide 46. A silicon nitride layer 47 is formed on the plate 12 and by suitable

masking and etching, windows 51, 52 and 53, 54 are formed to expose the contact regions 36, 37 and 38, 39. The mirrors 17, 18 are defined by etching the slots 56 leaving silicon nitride strips 57, which serve as hinges. The etching removes the silicon from beneath the hinges while leaving the silicon under the mirror surfaces to provide a rigid mirror. After the mirrors have been defined, a conductive layer is deposited on the top of the silicon plate to provide, on the surface of the mirrors, a reflective surface and one plate of a capacitor which cooperates with the conductive regions 31, 32 and 33, 34 to provide electrostatic forces which cause the mirrors to rotate at the hinges. Actuation of the mirrors is accomplished by applying voltages between the conductive film on the surface of the mirror and the individual implanted regions 31, 32 and 33, 34. The conductive film also covers the implanted contact regions 36, 37 and 38, 39. The film at the upper surface of the plate is not in contact with the film at the contact areas.

The off-axis zone plate lens, Fig. 6, is fabricated using electron beam lithographic pattern transfer and anisotropic reactive ion etching. The angles at which the light beam enters and exits the lens are specifically designed so that the beam emitted from the lens is well focused throughout the field of view, with no second order aberrations. The local structure of the lens grating has itself been optimized to increase the efficiency of the lens relative to a similar lens designed for on-axis imaging.

The quality of the image formed by the microscope is governed by the design of the lens. Traditional microscope objectives have many glass elements all of which are combined to reduce the aberration of the image to a minimum. For this invention, one benefits from the use of a very simple, single element objective. Because a laser source illumination at a single wavelength of light is used, one can use a diffractive lens rather than the more usual refractive type. This is a distinct advantage from a manufacturing point of view since a diffractive lens can be made lithographically with tight control over the pertinent design parameters. One gives up, however, the expectation of performing aberration-free imaging when one chooses to implement the microscope with a single diffractive lens element.

The aberrations of axially symmetric grating lenses are well known. For this application, one desires high resolution and, therefore, high numerical aperture in the

objective lens. The primary aberration (so-called third order aberration) that limits numerical aperture in an axially symmetric grating lens with the stop at the lens is coma.

With the zigzag optical path used for the microscope, one requires a lens that is not axially symmetric, but is designed to create an image from a beam of light that is incident at an angle from the lens normal. In general, such an off-axis lens will suffer from a more serious second order aberration called linear astigmatism. It has been discovered, however, that if the angles of incidence of the object beam and the image beam are chosen properly then the second order astigmatism disappears and imaging is again governed by third order coma. The constraint on the angles is that

$$\sin(\alpha_1)/r_1 = \sin(\alpha_2)/r_2 \quad (1)$$

where the angles α_1 , α_2 , r_1 and r_2 are defined in Figure 7.

The phase function of this lens is such that the points in the center of the field of view, P_1 and P_2 are perfect images of one another.

When the microscope is constructed with regard to this constraint on the angles made by the incoming and exiting beams with the normal to the lens plane, then the imaging aberrations of the off-axis lens are quite similar to the aberrations of the more familiar, axially symmetric lens. Any significant deviation from this relationship would result in an instrument with extremely poor performance, and therefore the geometric relationship described above is paramount to the operation of the microscope. On the other hand, the fact that there exists a situation favorable to off-axis imaging enables one to implement the microscope with a zigzag optical path, keeping the overall dimensions very small and the design simple.

Note finally from the figure that the object and image planes are normal to the direction the beam of light is traveling. This is important for a reflection microscope, since the lens must collect the light reflected from the sample. If the sample plane was tilted with respect to the incoming beam, then the reflected light would not retrace its path back into the lens.

The single mode optical fiber illumination/detection system is shown in Figure 8. A light source 61, such as a 3 mw helium-neon laser at 632.8 nm supplies light to one end of a single-mode optical fiber 62 which is used as a flexible conduit to deliver light to the fiber 13 which serves as the point source and detector for confocal operation of the microscope. The single lens focuses the light from the fiber onto the sample and collects the back-scattered light. A directional coupler 63 directs the reflected light from the sample onto photodetector 64 to provide an output signal 66.

The scanning microscope electronic interface is simple in principle. Referring to Figures 9 and 10, each scanning mirror is driven by two symmetrically placed electrodes 31, 32 and 33, 34, one on either side of the rotational axis. Application of a voltage between the electrode and the mirror plate results in an attractive electrostatic force proportional to the square of the magnitude of the voltage. To tilt the mirror one way or the other, a voltage is applied to one electrode at a time causing the mirror to deflect toward that electrode. For oscillatory motion in the x and y direction, a sinusoidal drive voltage 67 is applied to one of the electrodes 31, 33 with a DC bias sufficient to keep the voltage always positive. The opposing electrodes 32, 34 receive a drive voltage 68 with the opposite phase, so that as one side of an electrode sees the maximum voltage the other side sees zero voltage resulting in a net torsional force at the mirror. The frequency of the drive signal may be adjusted to cause the mirror to oscillate at its natural resonance or off resonance. Near resonance, the motion of the mirror will be phase shifted relative to the drive voltage waveform. In order to form an image from the detected light reflected from the sample, it is necessary to know the precise position of the mirror. A scan converter 69 is used for this purpose, which takes as its input the drive signals and the detected optical signal from the fiber, and produces as its output a raster scanned image suitable to display on a monitor 71 or for capture on a computer 72.

There are two possible control schemes. The simplest is *open loop control*, Figure 9, where it is assumed that the kinetic response to the mirrors is known well enough that one only need to monitor the drive voltage in order to predict the mirror position. Then the scan converter maps the intensity of the detected optical signal to

the calculated position of the beam. The other scheme is *closed loop control*, Figure 10, where the position of the mirrors is independently monitored and this information is used in a feedback scheme that attempts to lock the motion of the mirrors to the drive voltage waveform. One of the simplest ways to monitor the position of the mirror is to measure the capacitance between the mirror plate and the drive electrodes. This capacitance will vary with the angular position of the mirror, so that monitoring the capacitance fluctuation provides a direct measure of the mirror position. With closed loop control, the control loop is capable of making the mirror motion exactly follow the drive voltage, so that the scan converter may use the x and y drive signals directly to map the intensity to the proper position of the beam, without any specific knowledge of the mirror kinetics.

A microscope was constructed which was 6 mm long, 2.5 mm wide and 1 mm high. The scanning mirror 17 was $300\ \mu\text{m}$ by $360\ \mu\text{m}$ and the scanning mirror 18 was $500\ \mu\text{m}$ by $600\ \mu\text{m}$. The single mode optical fiber 13 was $125\ \mu\text{m}$ in diameter.

The microscope was operated to provide both raster-scan and lissajous-scan images. In the first example, the microscope was used to scan a glass substrate provided with chrome lines $2\ \mu\text{m}$ wide on $4\ \mu\text{m}$ centers and a $5\ \mu\text{m}$ line. The mirror 17 was scanned at a frequency of 2.71 kHz with approximately 20V peak-to-peak sinusoidal voltage. The mirror 18 was driven at a frequency of 5 Hz with approximately 25 peak-to-peak sinusoidal voltage. The field of view was $30 \times 24\ \mu\text{m}$. The resulting raster-scan image is shown in Figure 11, which has 271 lines/frame at a frame rate of 5 Hz. The $2\ \mu\text{m}$ lines are shown at 76 and the $5\ \mu\text{m}$ line is shown at 77.

In the second example, the microscope was used to scan a glass substrate with chrome lines $2\ \mu\text{m}$ wide on $4\ \mu\text{m}$ centers and $5\ \mu\text{m}$ lines on $10\ \mu\text{m}$ centers. The mirror 17 was scanned at a frequency of 4.3 kHz with approximately 30V peak-to-peak sinusoidal voltage. The mirror 18 was driven at a frequency of 1.07 kHz with approximately 25V peak-to-peak sinusoidal voltage. The field of view was about $80\ \mu\text{m} \times 60\ \mu\text{m}$. The resulting lissajous-scan image is shown in Figure 12. The frame rate was 8 Hz with 268 lines/frame. The $2\ \mu\text{m}$ and $5\ \mu\text{m}$ lines are shown at 78 and 79.

In another example, the microscope was used to scan an etched silicon test structure having U-shaped trenches. The mirror 17 was scanned at a frequency of 4.3 kHz with 30V peak-to-peak sinusoidal voltage, giving a field of view of $80\text{ }\mu\text{m} \times 60\text{ }\mu\text{m}$. The resulting Lissajous-scan image is shown in Figure 13. The trenches are shown at 81. The frame rate was 8 Hz with 268 lines/frame.

In a fourth example, the microscope was used to scan red blood cells on a glass slide. The mirror 17 was scanned at a frequency of 4.3 kHz with a 30V peak-to-peak sinusoidal drive voltage. The mirror 18 was driven at a frequency of 1.07 kHz with a 15V peak-to-peak drive voltage. The field of view was $40\text{ }\mu\text{m} \times 60\text{ }\mu\text{m}$. The resulting Lissajous-scan image is shown in Figure 14. The red cells are shown at 82. The frame rate was 8 Hz with 268 lines/frame.

Figures 15-17 show another embodiment of electrostatically rotated scanning mirrors for miniature scanning confocal microscope in accordance with the present invention. A bonded wafer technique was employed to fabricate the electrostatically deflected mirror assembly. A substrate 11a was prepared with a clearance well 86. Then a second silicon wafer 12a was bonded to the substrate. The silicon wafer was micromachined to form the mirror plates. The mirrors 17a, 18a, each consist of a silicon plate. Note, silicon plate 89 is shown in Figure 16, supported by torsion hinges 91, 92, and 93, 94. The hinges are made of a low stress silicon nitride. In one example, the mirrors were $500\text{ }\mu\text{m}$ by $500\text{ }\mu\text{m}$ and $25\text{ }\mu\text{m}$ thick. The mirrors were separated from the silicon substrate 12a by a gap of approximately $25\text{ }\mu\text{m}$. The mirrors were actuated by electrostatic attractive forces when a voltage was applied across the gap between reflecting metal electrodes 96, 97 and 98, 99 formed on top of the top surface of the silicon plates. The metal electrodes serve both as the reflective mirror surface and as a drive electrode for actuation of the mirror on its hinges. Connection to the two sets of electrodes is made by leads 101, 102, 103, 104 formed as a thin film on the top surface of the silicon nitride layer.

The starting material for the substrate 11a was [100] *p*-type silicon, $0.1\text{ }\Omega\text{-cm}$. The substrate was prepared with a thin thermal oxide layer for bonding and then the well 86 was patterned and etched into the substrate to the desired depth using reactive

ion etching. The starting material for the top plate wafer 12a was [111] *p*-type silicon, 5000 Ω -cm. It was also prepared with a thermal oxide layer and then bonded to the substrate 11a using a fusion bonding technique. The top plate was ground and polished to the desired final plate thickness of 25 μ m. A 1000 Å thermal oxide layer was deposited followed by a 1 μ m film 105 of low stress silicon nitride for the hinge material. Next, contact openings were patterned and etched through the silicon nitride and the underlying oxide, followed by a phosphorus implant and anneal to define *n*+ regions 106, 107 forming *pn* junctions between the metal electrodes 98, 99 and the *p*-type plate. Similar implant regions and *pn* junctions (not shown) were formed between the electrodes 96, 97 and the underlying *p*-type plate. The mirror outlines and hinges were then patterned and etched into the nitride layer, followed by deposition and patterning of the chrome-gold reflective electrodes. Finally, the silicon was etched anisotropically around the perimeter of the mirrors and beneath the hinges using a mixture of hydrofluoric, nitric and acetic acids (HNA), and the structure was released by etching the underlying bonding oxide. The complete substructure is shown in Figures 15-17.

Using a silicon plate for the mirror, insures a rigid, optically flat surface that did not distort during scanning and at a thickness of 25 μ m. It suffered minimal bowing from the intrinsic stress in the silicon nitride film. To actuate the plate, it is necessary to establish a voltage across the gap between the plate and the substrate. In order to accomplish this using electrodes deposited on the top of the plate, the silicon support or wafer must be depleted of free carriers beneath the driving electrode. To assure depletion through the 25 μ m thick plate, high resistivity silicon was used for the plate. The metal electrodes as described were electrically connected to the silicon plate through a *pn* junction as illustrated in Figures 16. When a voltage difference was applied between the driving electrodes, the *pn* junction under the more positive electrode was reversed biased and the full region beneath the electrode was depleted to a depth *W* given approximately by the formula

$$W = (2\epsilon(V - V_{bi})/qn_a)^{1/2} \quad (2)$$

where ϵ is the permittivity of silicon, V is the applied voltage, V_{bi} is the built in junction potential, q is the electron charge and n_a is the acceptor concentration for p -type silicon.

With selected resistivity for the mirror plates, the p -type silicon resistivity corresponds to an acceptor concentration of $n_a = 2.6 \times 10^{12} \text{ cm}^{-3}$. Using the above relationship, the plate will be fully depleted for a differential voltage between the electrodes of approximately 2.5 volts. The electrostatically deflected mirror assembly describe in connection with Figures 15-17 simplifies the construction of a scanning mirror arrangement by eliminating the need for implanted regions and simplifies the electrical connections for application of deflection voltages. In other respects, the microscope operates in a manner previously described.

Rather than employing the fiber coupler 63 shown in Figure 8, the confocal scanning microscope may employ a single mode optical fiber solely for the transmission of light to the scanning mirrors. A diode detector 64 may be placed adjacent to the inclined end 110 of the single mode fiber and a thin metal film dot beamsplitter 111 can be formed on the inclined end 110 of the fiber, Figures 18 and 19. The beam reflected from the object will then strike the inclined face of the fiber and be reflected downward by the metal beamsplitter to the diode 64 which will provide an output signal 66. By making the metal film the diameter to the fiber core, one will only get a signal from the diode 64 when the beam is focused on the core. The system acts as a confocal microscope. To eliminate reflectivity from the cladding surrounding the core of the fiber, the fiber may be provided with an anti-reflection coating (not shown).

The off-axis diffractive lens, Figure 6, can be replaced by a refractive lens in the form of a glass sphere 112, Figure 20, formed from a material with a high index of refraction and small dispersion such as zirconia, where $n=2.2$ to minimize aberrations. The sphere would be in the order of 1 mm diameter and held by lens holder 113. Other configurations could incorporate a tilted hemisphere which would give even less aberration. The surface of the scan mirrors can be modified to include a reflective diffractive lens (not shown) or a reflective phase plate (not shown). The purpose of such modification could be to replace the fixed lens or to function in concert with the fixed lens to provide aberration compensation.

We have found that the microscope can be shortened by replacing the two mirror arrangement with a biaxial mirror arrangement such as that illustrated in Figures 21-23. In Figure 21, like reference numerals have been applied to the same parts as described with reference to Figures 1-6. The assembly is simplified in that it requires only one metallized mirror for deflecting the beam in both the x and y direction. The system is made by mounting the mirror 116 on hinges 117, 118 to a frame 121 supported by hinges 122, 123 from the plate 12a. The mirror consists of a silicon plate 126 supported by torsion hinges 117, 118 made of low stress silicon nitride. Frame and mirror plate are separated from the silicon substrate by a gap of approximately $25\text{ }\mu\text{m}$.

The mirrors are actuated by the electrostatic attractive forces when a voltage is applied across the gap. Two metal electrodes, 136, 137 serve both as a reflective mirror surface and as a drive electrodes for actuation of the mirror on the hinges 117, 118. Two additional electrodes 138, 139 on the frame are used for actuation of the frame in an orthogonal direction. Connection to both sets of electrodes are made by wires 141, 142, 143, 144 bonded to the electrodes and to thin film leads 146, 147, 148, 149 formed on the surface of the nitride film to be described. As before, the substrate was highly doped *p*-type silicon, $0.1\text{ }\Omega\text{-cm}$. The substrate was prepared with a thin thermal oxide layer for bonding and then the well 151 was patterned and etched into the substrate to the desired depth, $25\text{ }\mu\text{m}$, using reactive etching. The starting material for the top plate was a substantially intrinsic *p*-type silicon, $5000\text{ }\Omega\text{-cm}$. It was also prepared with a thermal oxide and bonded to the substrate using a fusion bonding technique. The top plate was then ground and polished to the desired final plate thickness. A $1000\text{ }\text{\AA}$ thermal oxide layer was deposited followed by a $1\text{ }\mu\text{m}$ of low stress silicon nitride for the hinge material. Next the contact openings for the *pn* junction were patterned and etched to the silicon nitride and underlying oxide followed by phosphorus implant anneal to define an *n*+ region beneath the contacts. The mirror outlines and hinges were patterned and etched into silicon nitride followed by deposition and patterning of chrome-gold electrodes. Finally, the silicon was etched anisotropically around the perimeter of the mirror and underneath the hinges using a

mixture of hydrofluoric, nitric and acetic acids and the structure was released. The completed structure is shown in the Figures 22 and 23.

We have characterized the scan mirror in terms of their frequency response, and angular displacement as a function of applied drive signal. The dynamic behavior of the mirrors can be described, in the absence of damping, using the second order equation of motion given by

$$T = I_p \ddot{\Theta} + \frac{2KG}{l} \Theta \quad (3)$$

where I_p is the moment of inertia of either the plate or the plate and frame combined for motion about the inner and outer hinge axes, respectively. For the motion of the inner plate with dimension c along the hinge axis and b transverse to the axis, we have

10 $I_p = pcb^3t/12$ where t is the plate thickness and p is the density of silicon (2.32 g/cm^3). The restoring torque of the nitride membrane hinges is $\theta 2KG/l$, where l is the hinge length, and G is the elastic modulus of the membrane in shear, which is related to the tensile elastic modulus E (Young's modulus) by Poisson's ratio ν according to $G = E/2(1+\nu)$. The factor K is related to the polar moment of inertia of the nitride

15 support arm. For a rectangular cross section, K is give by ¹⁰

$$K = a\delta^3 \left[\frac{1}{3} - 0.21 \frac{\delta}{a} \left(1 - \frac{\delta^4}{12a^4} \right) \right] \quad (4)$$

where a is the width of the hinge and δ is the thickness of the nitride layer.

The torque on the plate is given by

$$T = \int F(x) x dA \quad (5)$$

where x is assumed to be in the direction transverse to the hinge axis, and $F(x)$ is the force per unit area, which can be written, for the range θ of through which the biaxial mirror can rotate, as

$$F(x) = \frac{1}{2} \frac{\epsilon_0 V^2}{(s_0 - x\theta)^2}. \quad (6)$$

In this equation $\delta\theta$ is the separation between the plate and the substrate.

- 5 Because the electrostatic forces are a function of the square of the applied voltage, it is often desirable to operate the device with a dc bias on the electrodes, so that the voltage is unipolar and the mirror response is at the same frequency as the drive voltage rather than twice that frequency. The presence of a dc bias will, however, alter the resonant frequency of the mirror. To see this effect, consider the behavior of the
- 10 inner plate. One can let the voltage across the gap $V - v_{dc}$ be constant across the plate, and then expand the expression for the torque as a function of θ . For a small angular displacements, this becomes

$$T_{dc} = \frac{1}{12} \frac{V_{dc}^2 \epsilon_0 b^3 c}{s_0^3} \theta + O(3) \quad (7)$$

where $O(3)$ means terms of order 3 or higher in θ . Now the equation of motion becomes

$$\frac{1}{12} \frac{V_{dc}^2 \epsilon_0 b^3 c}{s_0^3} \theta = I_p \ddot{\theta} + \frac{2KG}{l} \theta. \quad (8)$$

- 15 This structure will have a resonant frequency given by

$$\omega_0 = \left[\frac{2KG}{II_p} - \frac{V_{dc}^2 \epsilon_0}{\rho t s_0^3} \right]^{1/2}. \quad (9)$$

Increasing the DC bias voltage has the effect of lowering the resonant frequency of the mirror plate.

Figure 24 shows the frequency response of both the inner plate, and the combined inner plate and outer frame, for a particular mirror device. This data corresponds to a square mirror plat measuring 500 μm along a side and 25 μm thick. The hinge for the plate was 1 μm thick, 20 μm wide and 25 μm long. The outer frame is also square, with inner dimension 520 μm and outer dimension 720 μm . The hinge for the frame was 1 μm thick, 16 μm wide and 50 μm long.

Frequency data were measured for the inner plate of this particular mirror for a range of values of common mode dc bias voltage. In Figure 25, the dependence of resonant frequency upon the bias voltage, which is described by Equation 9, is illustrated by plotting the square of the frequency vs. The square of the bias voltage. For voltages small enough that the plate-substrate separation $\delta\theta$ is constant, this relationship is linear. The y intercept of the curve is equal to the spring constant of the hinges divided by the moment of inertia of the plate. We can use this number to calculate the shear modulus G for the silicon nitride hinges. For this device, we find that $G = 6.5 \times 10^{10}$ [N/m].

For real time, video rate scanning it is desirable to operate with a line scan frequency in the range of 8 to 10 kHz, and possibly higher for some applications. The highest resonant frequency we have measured with the current mirrors is 2.7 kHz. By increasing the hinge thickness to increase the spring constant, and decreasing the plate thickness to reduce the moment of inertia, this mirror architecture should easily scale to provide resonant line scanning at 10 kHz with a plate that measures 500 μm x 500 μm .

For raster type scanning using the biaxial mirror, the outer plate is typically operated well below resonance, at a few Hertz to tens of Hertz. In this frequency range, we can approximate $\theta \approx 0$, and the angular displacement of the mirror is governed by the static equation

$$\tau = \frac{2KG}{l} \theta. \quad (10)$$

We have measured the static displacement of the mirror and frame as a function of a dc voltage applied to one of the frame electrodes, with the center plate and the other frame electrodes all grounded. The results are plotted in Figure 26. Also plotted in the figure is the theoretically predicted deflection which is calculated by evaluating the integral of Equation 5 over one side of the outer frame. We then use the following expression for the torque with the torque T given by the relation

$$T = \frac{\epsilon_0 V^2}{2\Theta^2} \left[c_2 \left(\ln \left(1 - \frac{\Theta b_2}{2s_0} \right) + \frac{\Theta b_2/2s_0}{1 - \Theta b_2/2s_0} \right) - c_1 \left(\ln \left(1 - \frac{\Theta b_1}{2s_0} \right) + \frac{\Theta b_1/2s_0}{1 - \Theta b_1/2s_0} \right) \right] \quad (11)$$

where $b_1 = c_1 = 520 \mu\text{m}$ are the frame inside dimensions and $b_2 = c_2 = 720 \mu\text{m}$ are the frame outside dimensions. The only material parameter appearing in Equation 10 is the elastic shear modulus G . Using the number for G calculated from the frequency response data yields an excellent agreement between the theoretically predicted and measured static deflection as a function of applied drive voltage.

We have used the biaxial silicon torsional mirror as the scanning element in a microfabricated fiber confocal optical microscope^{6,7}. The device, which is illustrated in Figure 21, consists of a substrate wafer with the scan mirror fabricated on its surface, a second silicon wafer with a anisotropically etched cavity in which the light beam propagates, and a top plate made of used silica which contains the grating lens used to focus the light beam onto the sample being imaged. The light emerging from an angle polished single mode optical fiber is reflected from a stationary mirror on the etched cavity face, before it encounters the center plate of the biaxial scan mirror. The reflected light from the scan mirror passes through the objective lens and is focused to a spot on the sample. Light reflected from the sample is collected by the lens and retraces its path back into the fiber, where it is detected to generate a signal proportional to the sample reflectivity. Actuation of the scan mirror causes the focused spot to raster across the sample, and an image is formed point by point.

Figure 27 shows an image of a test pattern of chrome lines on a glass substrate that was obtained with the microfabricated microscope and the biaxial scan mirror. The wider lines are 5 μm wide on a 10 μm period, and the narrower lines are 2 μm wide on a 4 μm period. The numerical aperture of the lens is 0.25, and the focused spot is 1 μm fwhm. The field of view for this image is 60 μm X 60 μm (one division on the grid is 10 μm), corresponding to $\pm 1.5^\circ$ angular displacement of the scan mirror. This image was taken using a triangular frame scan at 10 Hz and a sinusoidal line scan at 1.8 kHz, without benefit of retrace blanking for either the line scan or the frame scan.

Referring to Figure 28, a micromachined microscope 155 in accordance with the present invention is shown mounted on a PZT Bimorph 156 inside a hypodermic needle tubing 157 having a window 158. By applying suitable voltages to the bimorph, the microscope 155 can be deflected to focus at various sample planes 159. The hypodermic tubing is shown mounted to a cable 161 which houses the optical fiber, the leads for driving the scan mirror electrodes, and receiving signals from the detector 64 from the scanning head. The micromachined confocal microscope can also be mounted for use in dentistry, dermatology, etc.

Although a specific embodiment of the invention has been provided, modifications can be made without departing from the invention. For example, the mirrors may be cantilevered or supported on a single post. There has been provided a miniature scanning confocal microscope making use of micro-machined scanning mirrors and parts.

The foregoing description of specific embodiments of the invention have been presented for the purpose of illustration and description. They are not intended to be exhaustive or to limit the invention to the precise forms disclosed, and obviously many modifications, embodiments, and variations are possible in light of the above teaching. It is intended that the scope of the invention be defined by the claims appended hereto and their equivalents.

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WHAT IS CLAIMED:

1. A scanning optical microscope of the type which includes a single mode optical fiber having one end which serves as point source of light, a lens for focusing light from the end of the fiber onto a point on a focal plane, and for gathering light reflected from said point and focusing said light onto the end of the optical fiber, characterized in that it includes:

a micromachined scanning mirror means comprising a silicon member,
silicon nitride hinges for supporting said mirror means for rotation about said hinges,

a reflective surface carried by said silicon member to receive the light from the fiber, and

means for electrostatically activating the mirror means to scan the light along a first direction and a second orthogonal direction whereby the point on the focal plane is scanned in said first and second directions and light is directed back from the focal plane to the end of the optical fiber via the lens and scanning mirror.

2. A scanning confocal microscope as in Claim 1 in which mirror means comprises a first micromachined scanning mirror to receive light from the optical fiber and scan the light along a first direction and a second micromachine scanning mirror to receive light from the first mirror and scan the light in an orthogonal direction.

3. A scanning optical microscope as in Claim 1 in which the mirror means comprises a frame which is supported by nitride hinges for rotation about a first axis, and a micromachined mirror supported from said frame by nitride hinges for rotation about an orthogonal axis and whereby said mirror scans the light at first and second orthogonal directions.

4. A scanning optical microscope as in Claim 1 in which the end of said optical fiber is inclined, a beamsplitter is disposed on the end of the optical fiber to reflect the

light received from said focal point onto a detector disposed adjacent to the end of the fiber.

5. A scanning optical microscope as in Claim 1 in which the lens is an off-axis binary lens.
6. A scanning optical microscope as in Claim 1 in which the lens is a refractive lens.
7. A scanning optical microscope as in Claim 1 in which a lens is carried by the silicon member.
8. A scanning optical microscope including:
 - a low resistivity substrate,
 - a low resistivity frame hingeably supported above said substrate for rotation about a first axis,
 - a high resistivity member hingeably supported above said substrate by said frame for rotation about a second orthogonal axis,
 - a pair of spaced conductive, reflective films carried on the surface of said high resistivity member whereby by selective application of voltage between said conductive films and said substrate, said member is electrostatically rotated about said first axis,
 - a pair of spaced conductive films carried on the surface of said frame whereby selective application of voltage between said conductive film and said substrate the frame is rotated about the second orthogonal axis, and
 - a lens for receiving the light scanned by said mirror and focusing it on an image plane for receiving light reflected from said plane and directing it back onto the mirror and optical fiber.
9. A scanning optical microscope as in Claim 8 in which the end of said optical fiber is inclined, a beamsplitter is disposed on the end of the optical fiber to reflect the

light received from said focal point onto a detector disposed adjacent to the end of the fiber.

10. A scanning optical microscope as in Claim 8 in which the lens is an off-axis binary lens.

11. A scanning optical microscope as in Claim 8 in which the lens is a refractive lens.

12. A scanning optical microscope as in Claim 8 in which a lens is carried by the silicon member.

13. A scanning optical microscope as in Claim 8 in which said substrate and said member are silicon.

14. A scanning optical microscope as in Claim 13 in which said means for hingeably supporting said frame and member are silicon nitride.

15. A scanning optical microscope of the type which includes a single mode optical fiber having one end which serves as point source of light, a lens for focusing light from the end of the fiber onto a point on a focal plane, and for gathering light reflected from said point and focusing said light onto the end of the optical fiber, characterized in that it includes:

a micromachined scanning mirror comprising a first high resistivity silicon member as formed in a silicon plate,

a silicon nitride layer including silicon nitride hinges for supporting said mirror from said plate for rotation about a first axis,

a low resistivity substrate disposed adjacent to said mirror, and

spaced reflective conductive surfaces carried by the silicon member to receive the light from the fiber, said spaced reflective conductive surfaces and said substrate

providing means for rotating the mirror responsive to voltages applied between said conductive surfaces and the substrate.

16. A scanning confocal microscope as in Claim 15 in which a second mirror comprising a second high resistivity silicon member formed in said silicon plate, a silicon nitride layer including silicon nitride hinges for supporting said mirror from said plate for rotation about a second orthogonal axis, spaced reflective surfaces carried by the second high conductive resistivity member to receive light from the fiber, said spaced reflective conductive surfaces and said substrate providing means for electrostatically rotating the second mirror responsive to voltages applied between the conductive surfaces and the substrate whereby the combination of mirrors deflects the light in a first and second orthogonal direction.

17. A scanning optical microscope as in Claim 1 in which a silicon frame is formed in said silicon plate, silicon nitride hinges support said frame on said plate for rotation about an orthogonal axis, spaced conductive surfaces carried by said frame, spaced conductive surfaces and said substrate providing means for rotating the frame responsive to voltages applied between said conductive surfaces and the.

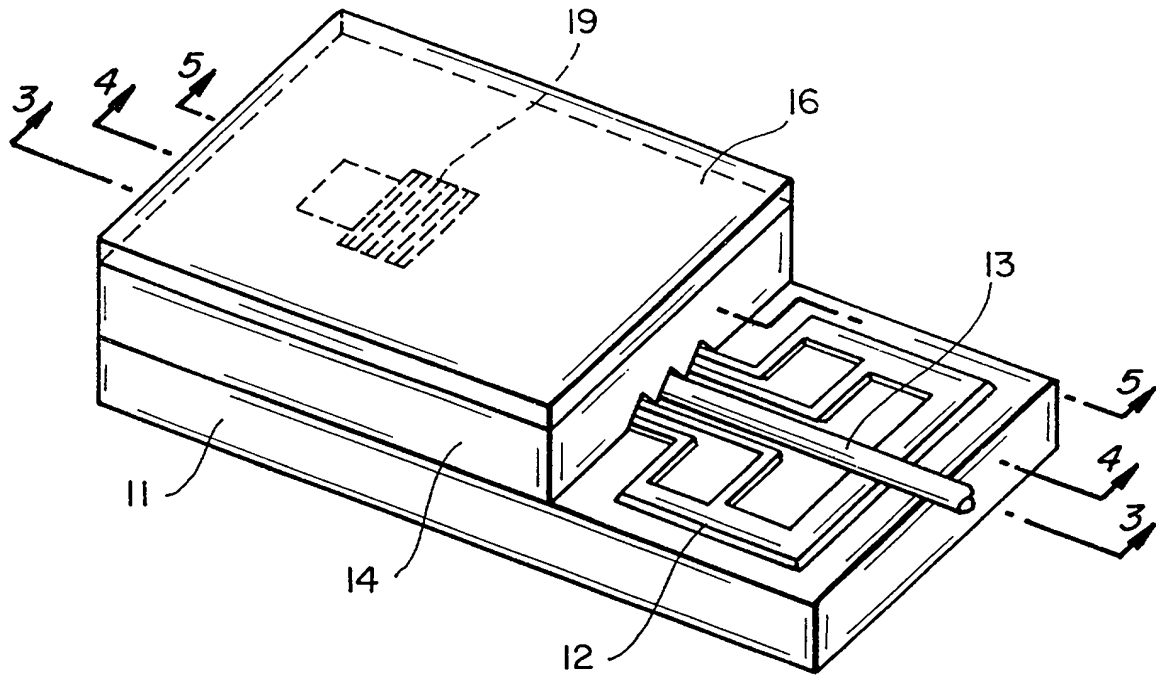
18. A scanning optical microscope as in Claim 8 including a *p-n* diode formed between spaced conductive surface carried by the high resistivity member and the high resistivity frame.

19. A scanning mirror comprising:
 a semiconductor plate,
 a thin film hinge for rotatably supporting said plate,
 at least two conductive electrodes carried by one surface of said semiconductor plate,
 a *p-n* junction formed between said conductive electrodes and said plate, and

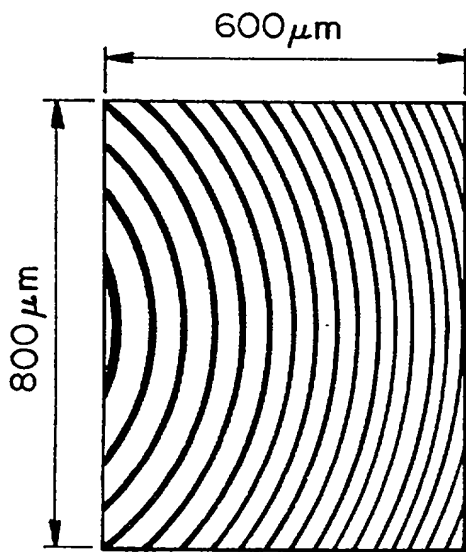
a conductive member spaced from the other surface of said plate whereby when a voltage is applied between the conductive electrodes and the conductive member, the region below the electrodes is depleted of free carriers and a torsional force is generated which causes the plate to rotate about its support hinge.

Country	1950	1960	1970	1980	1990	2000	2010	2020	2030	2040	2050
Japan	7.0	7.5	8.0	9.0	10.0	11.0	12.0	13.0	14.0	15.0	16.0
Germany	10.0	10.5	11.0	12.0	13.0	14.0	15.0	16.0	17.0	18.0	19.0
France	11.0	11.5	12.0	13.0	14.0	15.0	16.0	17.0	18.0	19.0	20.0
Italy	12.0	12.5	13.0	14.0	15.0	16.0	17.0	18.0	19.0	20.0	21.0
Spain	13.0	13.5	14.0	15.0	16.0	17.0	18.0	19.0	20.0	21.0	22.0
Sweden	14.0	14.5	15.0	16.0	17.0	18.0	19.0	20.0	21.0	22.0	23.0
Belgium	15.0	15.5	16.0	17.0	18.0	19.0	20.0	21.0	22.0	23.0	24.0
United Kingdom	16.0	16.5	17.0	18.0	19.0	20.0	21.0	22.0	23.0	24.0	25.0
Canada	17.0	17.5	18.0	19.0	20.0	21.0	22.0	23.0	24.0	25.0	26.0
United States	18.0	18.5	19.0	20.0	21.0	22.0	23.0	24.0	25.0	26.0	27.0
China	19.0	19.5	20.0	21.0	22.0	23.0	24.0	25.0	26.0	27.0	28.0
India	20.0	20.5	21.0	22.0	23.0	24.0	25.0	26.0	27.0	28.0	29.0
South Africa	21.0	21.5	22.0	23.0	24.0	25.0	26.0	27.0	28.0	29.0	30.0
South Korea	22.0	22.5	23.0	24.0	25.0	26.0	27.0	28.0	29.0	30.0	31.0
Poland	23.0	23.5	24.0	25.0	26.0	27.0	28.0	29.0	30.0	31.0	32.0
Ukraine	24.0	24.5	25.0	26.0	27.0	28.0	29.0	30.0	31.0	32.0	33.0
Russia	25.0	25.5	26.0	27.0	28.0	29.0	30.0	31.0	32.0	33.0	34.0
China (excl. HK)	26.0	26.5	27.0	28.0	29.0	30.0	31.0	32.0	33.0	34.0	35.0
China (incl. HK)	27.0	27.5	28.0	29.0	30.0	31.0	32.0	33.0	34.0	35.0	36.0
China (excl. HK) (excl. Tibet)	28.0	28.5	29.0	30.0	31.0	32.0	33.0	34.0	35.0	36.0	37.0
China (incl. HK) (excl. Tibet)	29.0	29.5	30.0	31.0	32.0	33.0	34.0	35.0	36.0	37.0	38.0
China (incl. HK) (incl. Tibet)	30.0	30.5	31.0	32.0	33.0	34.0	35.0	36.0	37.0	38.0	39.0
China (excl. HK) (incl. Tibet)	31.0	31.5	32.0	33.0	34.0	35.0	36.0	37.0	38.0	39.0	40.0
China (incl. HK) (incl. Tibet)	32.0	32.5	33.0	34.0	35.0	36.0	37.0	38.0	39.0	40.0	41.0
China (excl. HK) (excl. Tibet) (excl. Xinjiang)	33.0	33.5	34.0	35.0	36.0	37.0	38.0	39.0	40.0	41.0	42.0
China (incl. HK) (excl. Tibet) (excl. Xinjiang)	34.0	34.5	35.0	36.0	37.0	38.0	39.0	40.0	41.0	42.0	43.0
China (incl. HK) (incl. Tibet) (excl. Xinjiang)	35.0	35.5	36.0	37.0	38.0	39.0	40.0	41.0	42.0	43.0	44.0
China (incl. HK) (incl. Tibet) (incl. Xinjiang)	36.0	36.5	37.0	38.0	39.0	40.0	41.0	42.0	43.0	44.0	45.0
China (excl. HK) (incl. Tibet) (incl. Xinjiang)	37.0	37.5	38.0	39.0	40.0	41.0	42.0	43.0	44.0	45.0	46.0
China (incl. HK) (incl. Tibet) (incl. Xinjiang)	38.0	38.5	39.0	40.0	41.0	42.0	43.0	44.0			

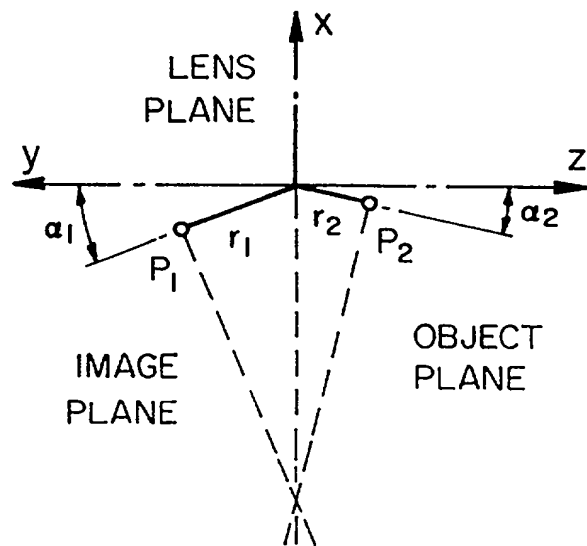
5



FIG_1



FIG_6



FIG_7

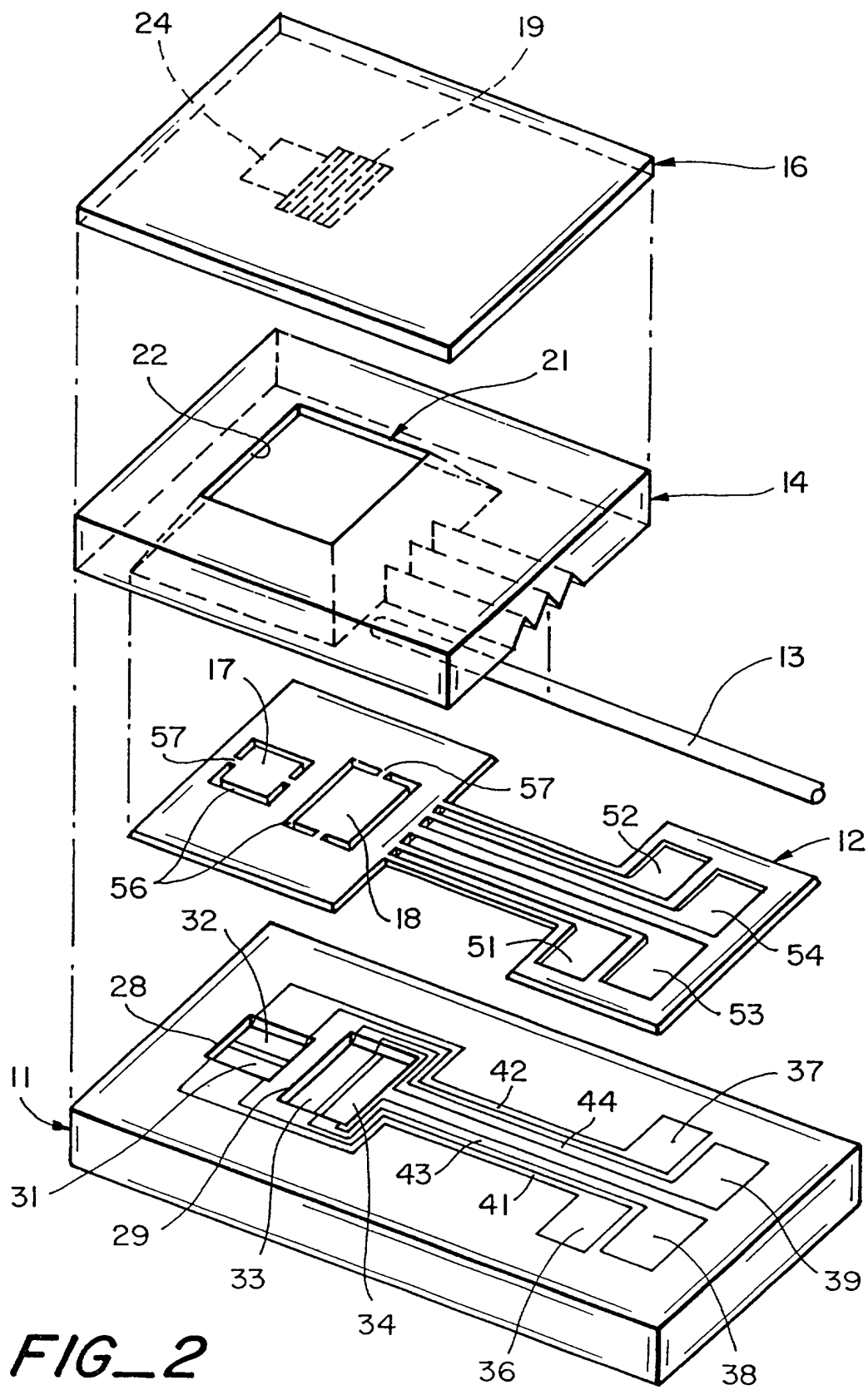
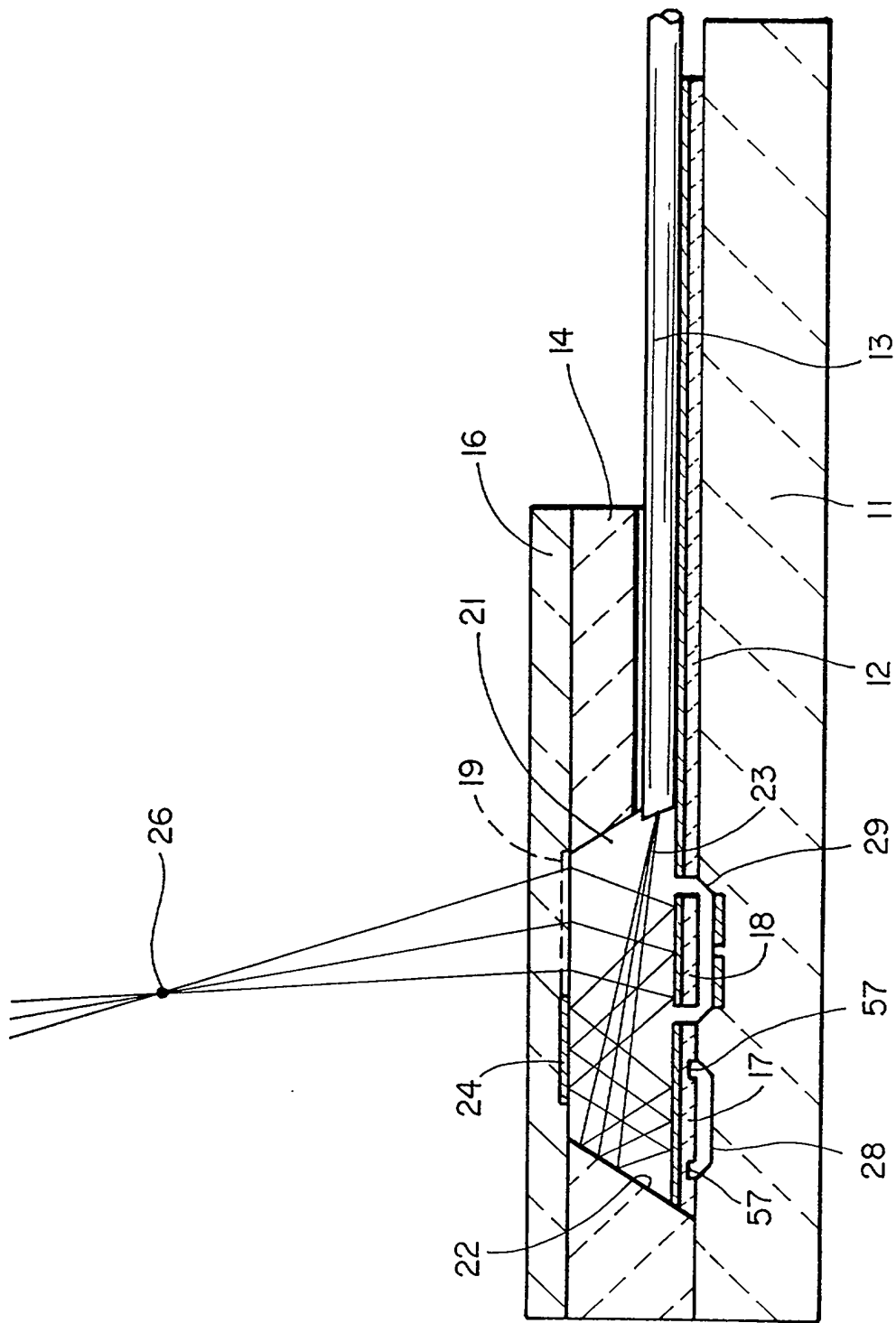
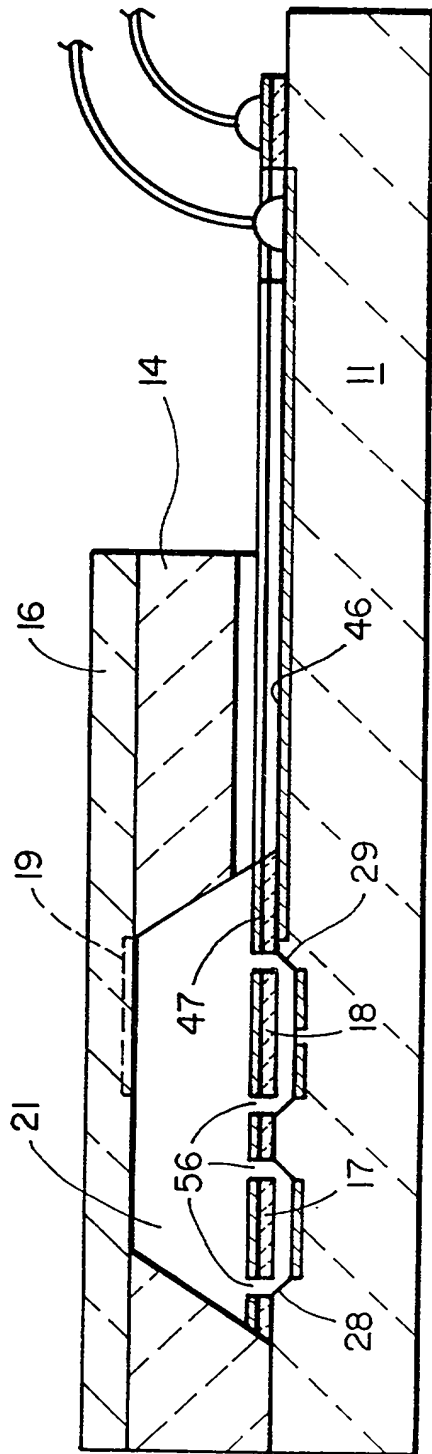


FIG. 2



FIG_3



FIG_4

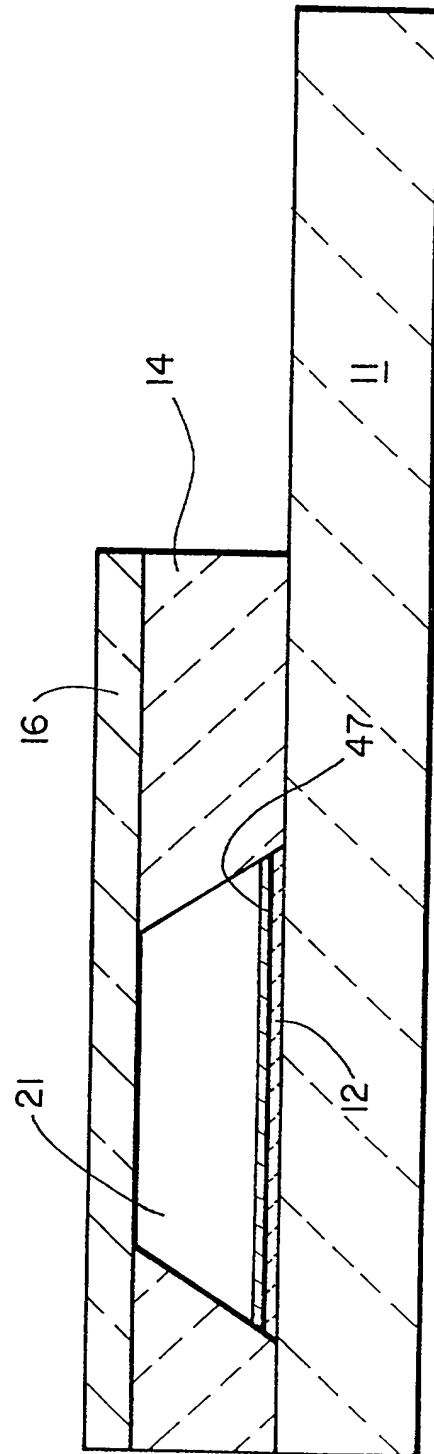


FIG-5

The diagram illustrates a fiber-optic system. A **LASER SOURCE** (61) emits light through a lens into a fiber (62). This fiber is connected to a **FIBER COUPLER** (63). The coupler splits the signal into two paths: one leading to **TO FIBER 13** and another leading to a **DUMP**. A **DETECTED OPTICAL SIGNAL** (66) is shown as a separate output path, with a component (64) likely representing a detector or sensor.

FIG_9

OPEN LOOP CONTROL SCHEME

The diagram illustrates the control scheme for a scanning system. It features two reference signals: **X SCAN REF.** and **Y SCAN REF.**.

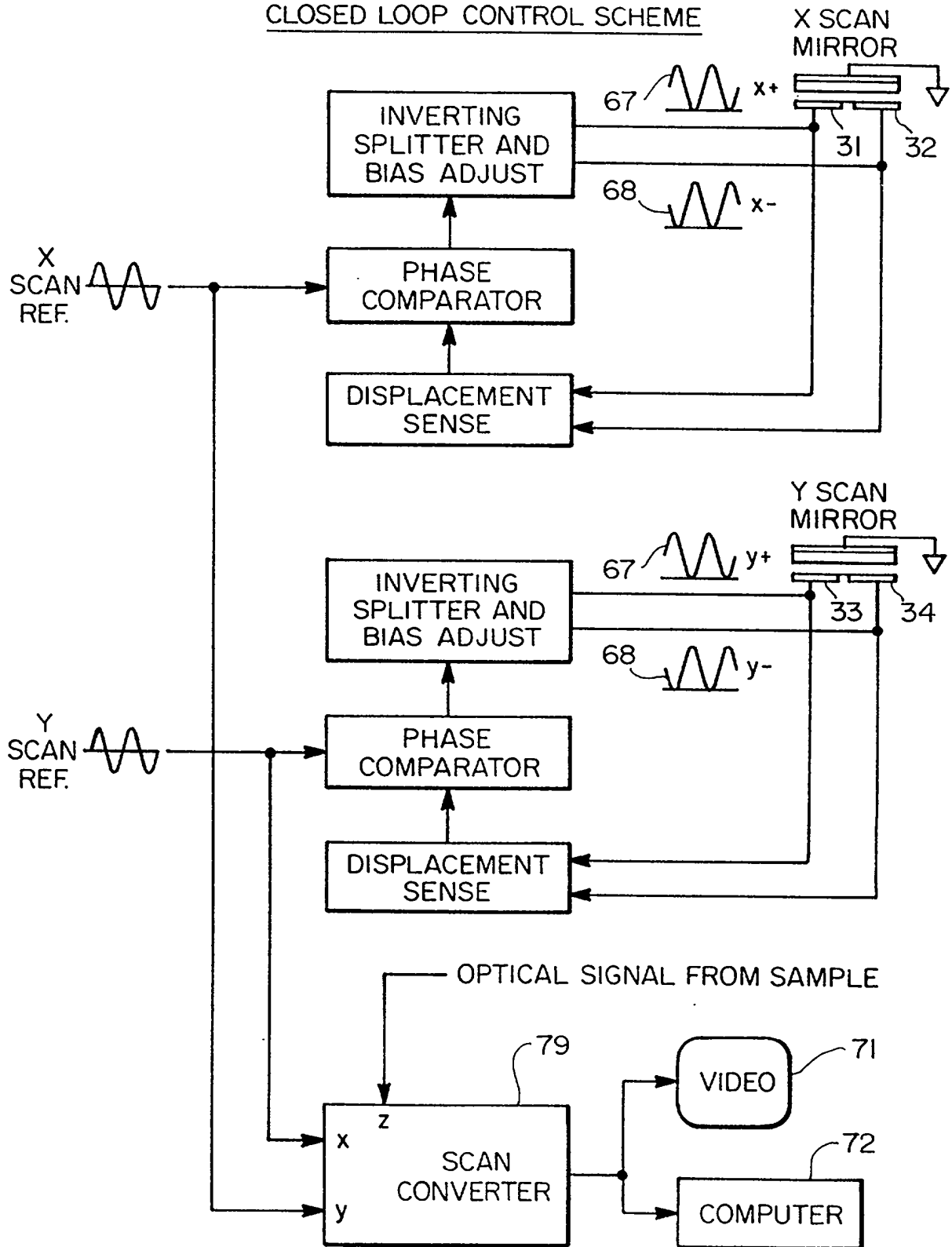
Each reference signal is split into two paths:

- Top Path:** The reference signal is fed into an **INVERTING SPLITTER AND BIAS ADJUST** block. This block outputs two signals, labeled **67** and **68**, which are then fed into the **X SCAN MIRROR** and **Y SCAN MIRROR** respectively.
- Bottom Path:** The reference signal is fed into a **SCAN CONVERTER** block (labeled **69**). This block also receives an **OPTICAL SIGNAL FROM SAMPLE** (labeled **z**). The **SCAN CONVERTER** outputs two signals, labeled **x** and **y**, which are then fed into the **X SCAN MIRROR** and **Y SCAN MIRROR** respectively.

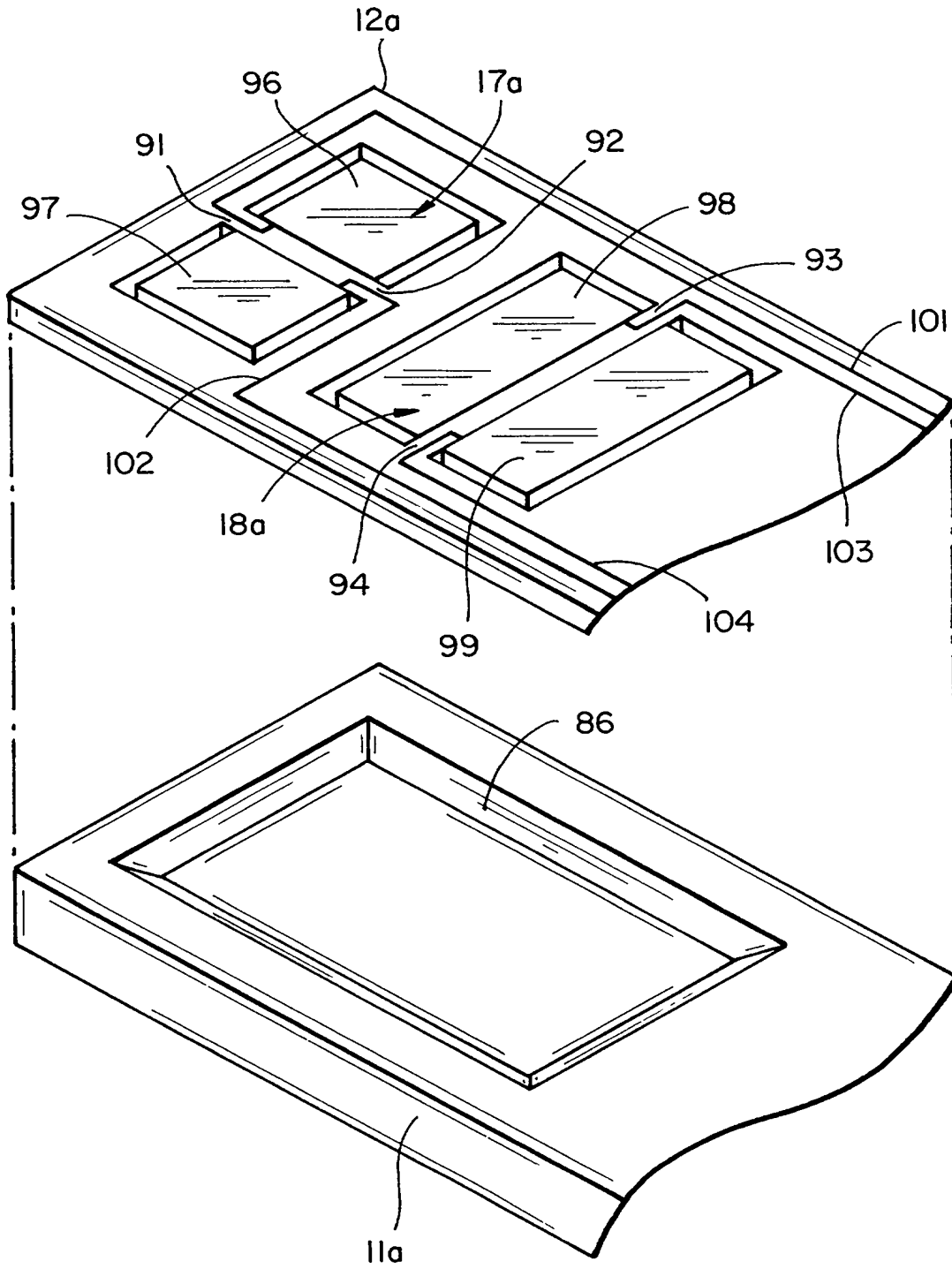
The **SCAN CONVERTER** also outputs two signals, labeled **71** and **72**, which are then fed into a **VIDEO** block and a **COMPUTER** block respectively.

FIG_9

CLOSED LOOP CONTROL SCHEME

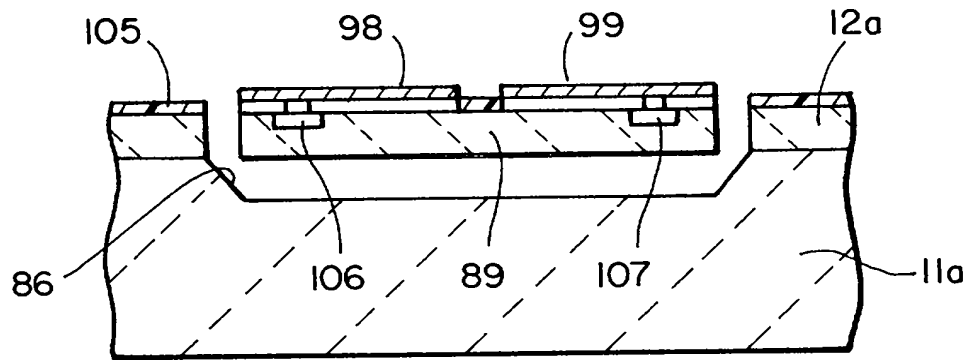


FIG_10

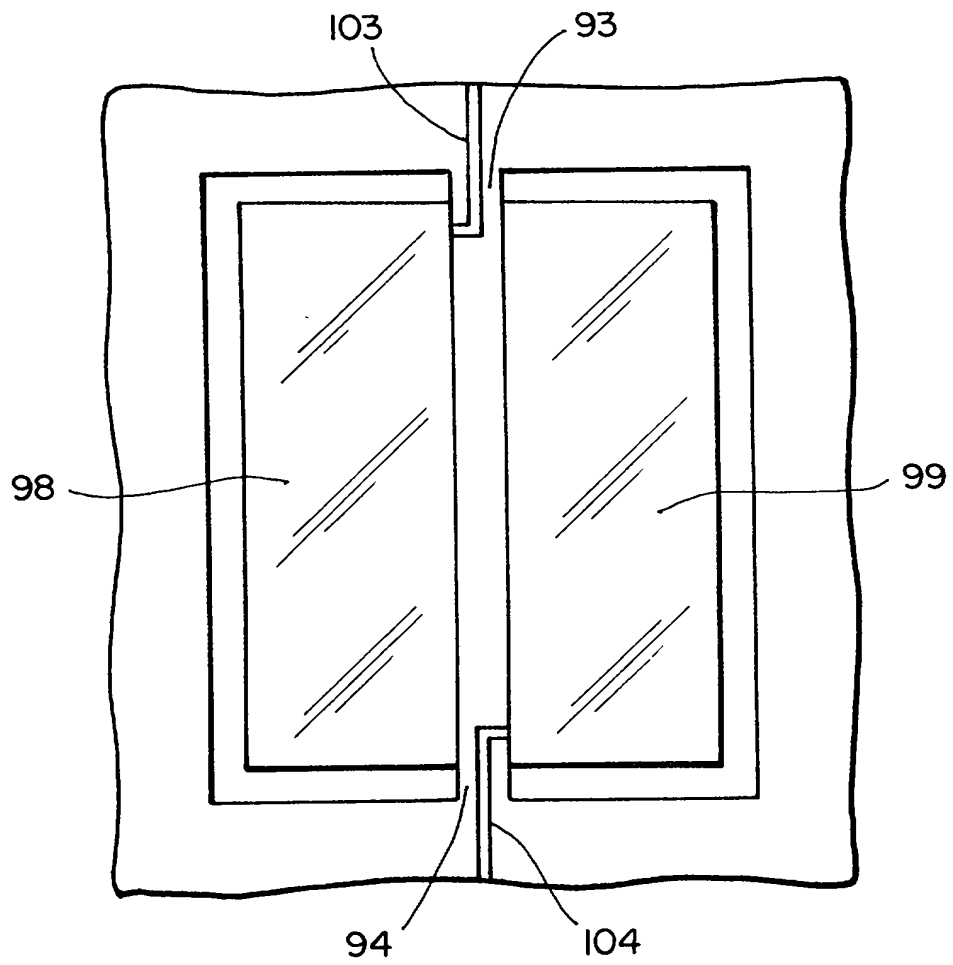


FIG_15

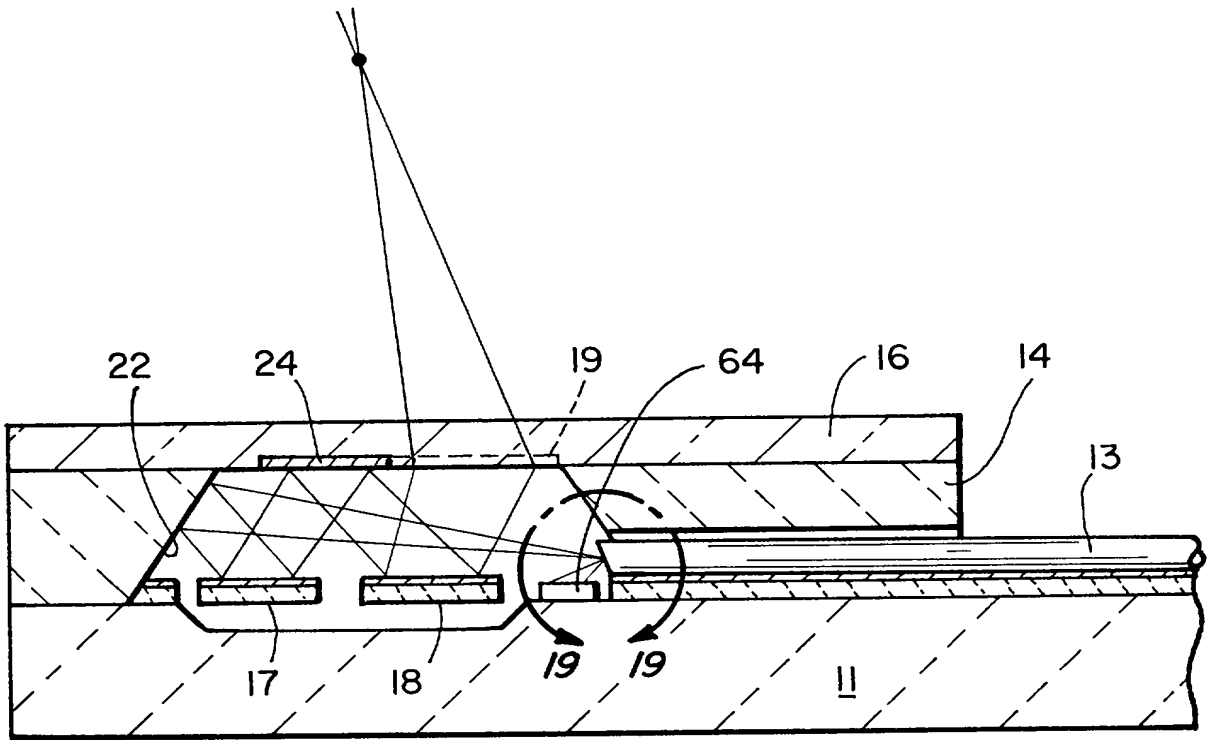
10/16



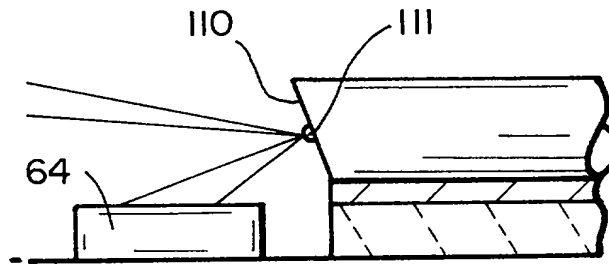
FIG_16



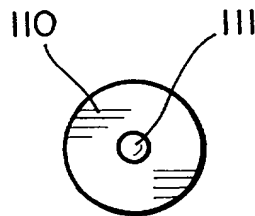
FIG_17



FIG_18



FIG_19a



FIG_19b



FIG_21



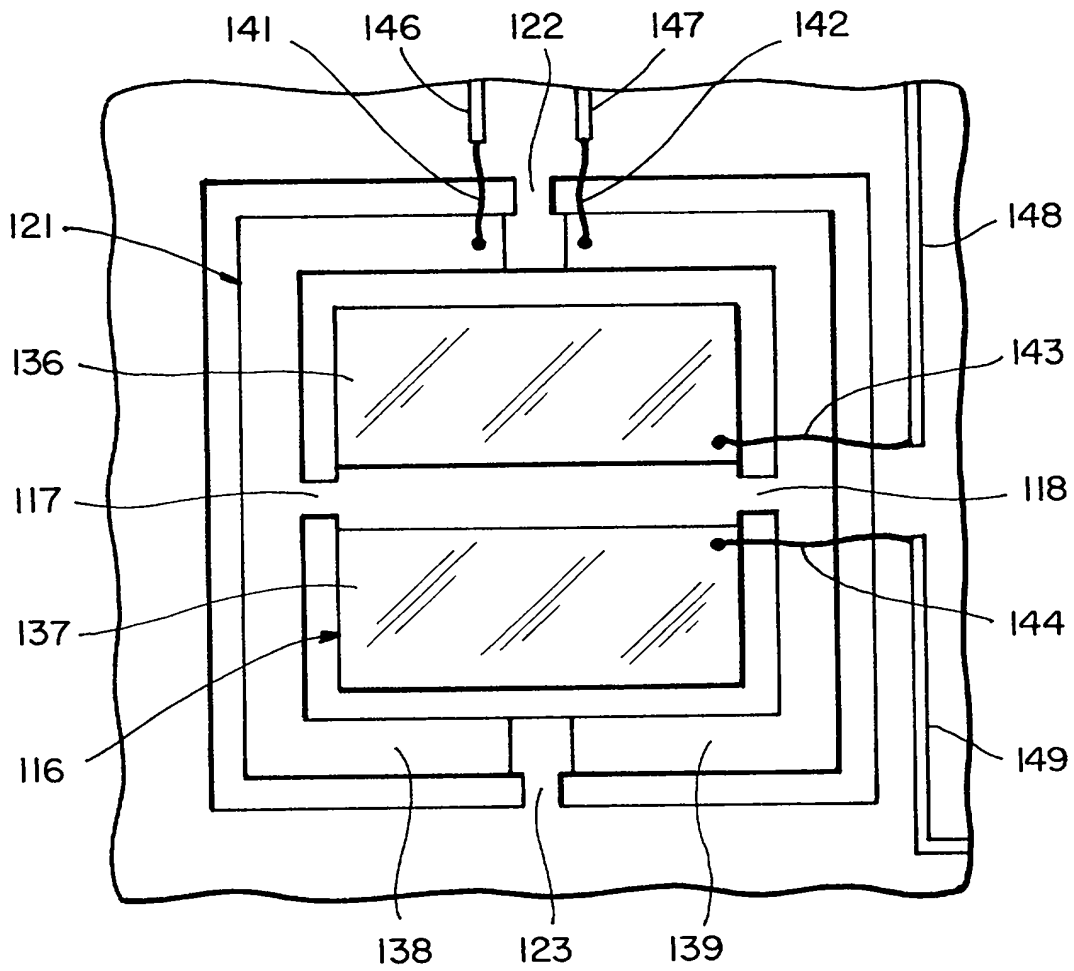


FIG. 22

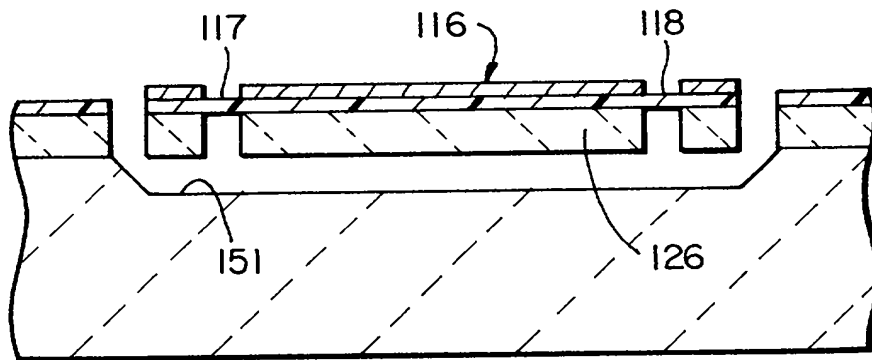
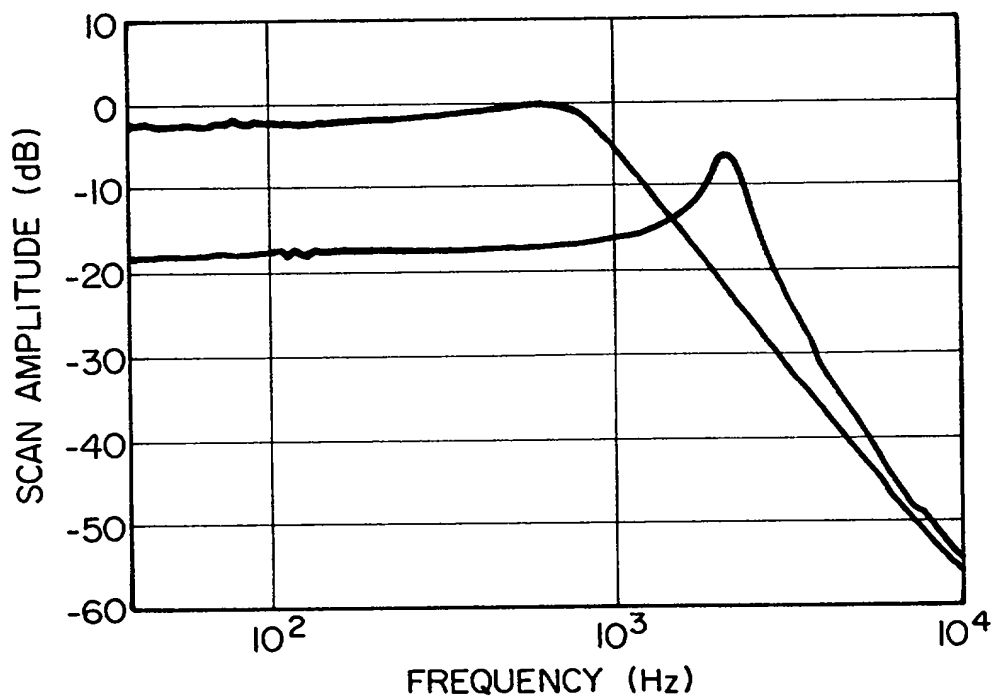
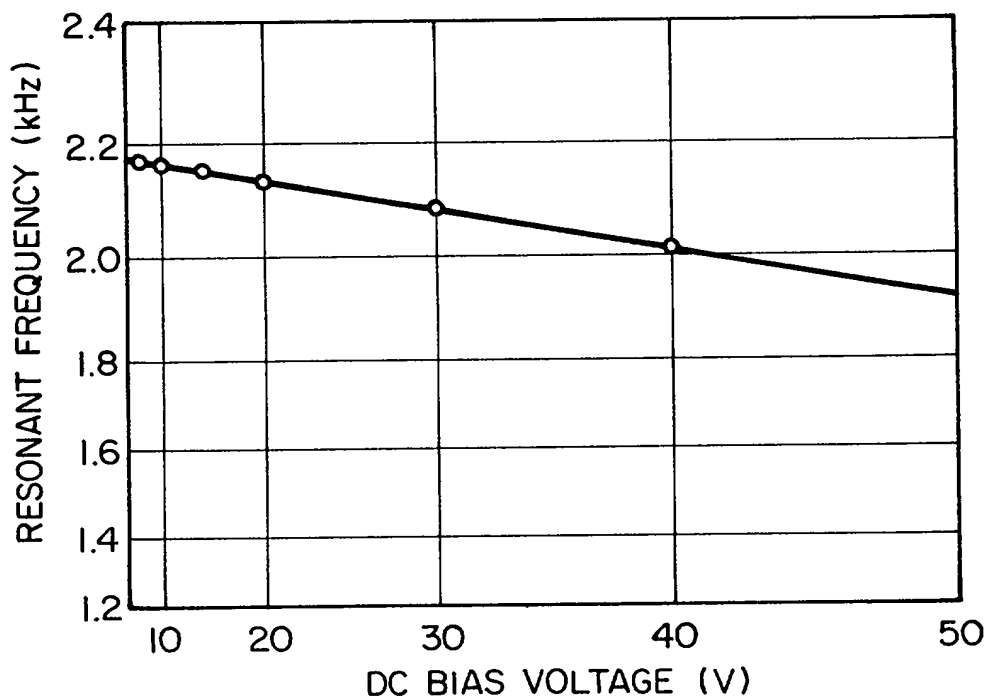
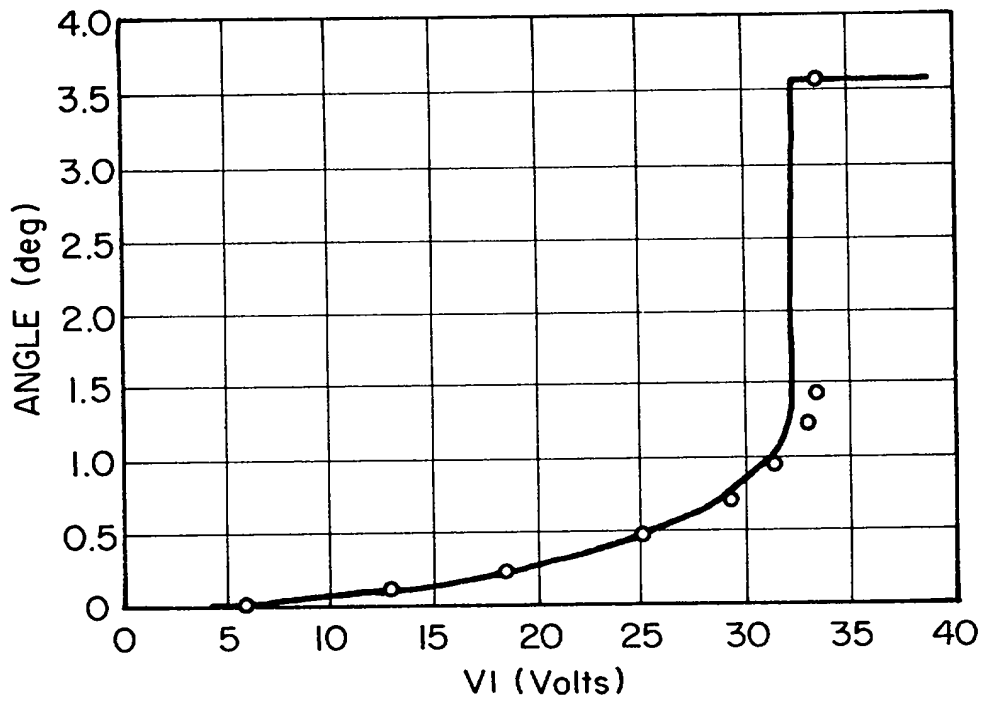
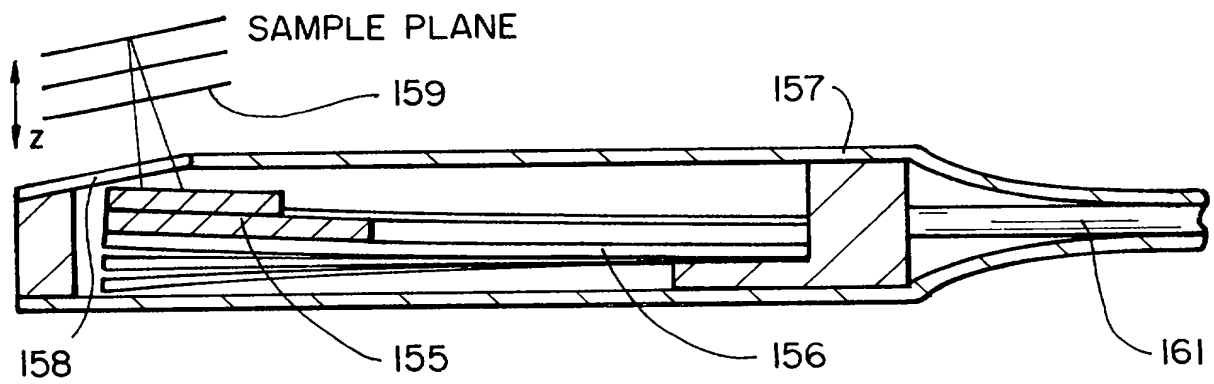


FIG. 23

**FIG_24****FIG_25**

**FIG_26****FIG_28**

DECLARATION FOR PATENT APPLICATION

As a below-named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled *Miniature Scanning Confocal Microscope*, the specification of which [x] is attached hereto (or) [] was filed on * under Application Serial No. * and was amended on or about *.

I hereby state that I reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose to the Patent Office all information known to me to be material to patentability as defined in 37 CFR §1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)

Priority Claimed

(Number)

(Country)

(Day/Month/Year Filed)

Yes

No

I hereby claim the benefit under Title 35, United States Code, §120 of any U.S. application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior U.S. application in the manner provided by the first paragraph of Title 35, U.S. Code, §112, I acknowledge the duty to disclose to the Patent Office all information known to me to be material to patentability as defined in 37 CFR §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

A-62591/AJT
(Atty Docket No.)

08/575,687
(Application No.)

December 19, 1995
(Filing Date)

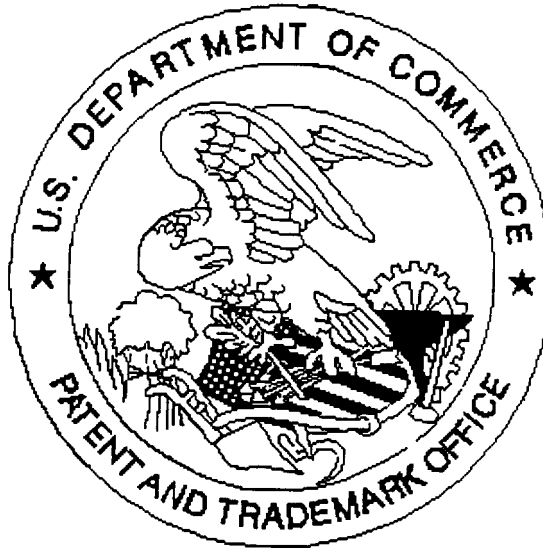
Pending
(Status)

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FLEHR HOHBACH TEST ALBRITTON & HERBERT LLP
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